

| | Hits | Search Text | DBs |
|----|------|---|---|
| 50 | 9 | ((photoresist or resist) near12 (pattern or mask) near16 (inkjet near4 print\$4) near26 (fill\$4 or provide or apply\$4 or liquid or supply\$4 or coat\$4 or deposit\$4)) same (conductive or metal\$4 or electro\$4conductive or organo\$3metal\$5)) and ((inkjet or (inkjet near9 printer)) same (ink or liquid) same (fill\$4 or coat\$4 or mist\$4 or atomizer)) and (heat\$4 or anneal\$4 or bak\$4) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 51 | 15 | ((photoresist or resist) near12 (pattern or mask)) same (inkjet near10 print\$4) near26 (fill\$4 or provide or apply\$4 or liquid or supply\$4 or coat\$4 or deposit\$4 or (shower near9 head)) same (conductive or metal\$4 or electro\$4conductive or organo\$3metal\$5)) and ((heat\$4 or anneal\$4 or bak\$4 or evaporat\$4) same (solvent or liquid)) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 52 | 34 | ((photoresist or resist) near12 (pattern or mask)) same (inkjet near10 print\$4) same (discharg\$4 or provide or apply\$4 or liquid or supply\$4 or coat\$4 or deposit\$4 or (shower near9 head)) same (conductive or metal\$4 or electro\$4conductive or organo\$3metal\$5 or ink)) and ((heat\$4 or anneal\$4 or bak\$4 or evaporat\$4) same (solvent or liquid)) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |

| | Hits | Search Text | DBs |
|----|------|---|---|
| 53 | 5 | ((photoresist or resist) near12 (pattern or mask)) same inkjet same (discharg\$4 or liquid or supply\$4 or coat\$4 or deposit\$4 or (shower near9 head)) same (conductive or metal\$4 or electro\$4conductive or organo\$3metal\$5 or ink) same fill\$4 same (opening or via or trench)) and ((heat\$4 or anneal\$4 or bak\$4 or evaporat\$4)) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 54 | 8 | ((photoresist or resist) near12 (pattern or mask)) same inkjet same (discharg\$4 or liquid or supply\$4 or coat\$4 or deposit\$4 or (shower near9 head)) same (liquid or material or ink)) and (fill\$4 same (opening or via or trench) same (electroconductive or conductive or metal\$4 or organometall\$3) same (heat\$4 or anneal\$4 or bak\$4 or evaporat\$4)) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 55 | 5 | ((photoresist or resist) near12 (pattern or mask)) same inkjet same (discharg\$4 or liquid or supply\$4 or coat\$4 or deposit\$4 or (shower near9 head)) same (liquid or material or ink)) and (fill\$4 same (opening or via or trench) same (pattern or mask) same (photoresist or resist) same (electroconductive or conductive or metal\$4 or organometall\$3) same (heat\$4 or anneal\$4 or bak\$4 or evaporat\$4)) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |